

# BSTMX16-1828 18-28 GHz I/Q Mixer Data Sheet

#### I. Product Introduction

BSTMX16-1828 is an I/Q image rejection mixer chip that integrates two passive double-balanced mixers and a 90° quadrature bridge.

The output of the intermediate frequency signal with the same amplitude and 90° phase difference is achieved by using

The image rejection function can be achieved by using a low-frequency quadrature coupler.

## **II. Key Technical Indicators**

•	RF & LO frequency:	18~28GHz
•	IF frequency:	DC-6GHz
•	Local oscillator power:	17dBm
•	Conversion loss:	9dB
•	LO/RF isolation:	35dB
•	Image suppression:	25dBc
•	Chip size:	1.4mmx1.1mm

### **III. Application Areas**

- Radar
- Communications
- Instruments



## IV. Absolute Maximum Ratings

Table 1

PARAMETER	LIMIT VALUE	
Maximum input power	+20dBm	
Storage temperature	-65 °C∼ +150 °C	
Operating temperature	-55 °C∼ +125 °C	

## V. Electrical Performance Table ( $T_A = 25$ °C)

Table 2

INDEX	MINIMUM	TYPICAL VALUES	MAXIMUM	
RF & LO frequency (GHz)	18 ~ 28			
IF frequency (GHz)	DC ~ 6			
Conversion loss (dB)	_	9	_	
LO~RF isolation (dB)	_	35	_	
LO~IF isolation (dB)	_	20	_	
RF~IF isolation (dB)	_	29	_	

## VI. Overall and Port Dimensions (mm)

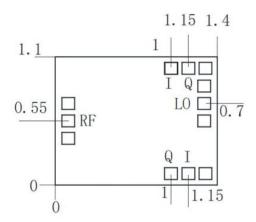


Figure 1



#### **VII. Precautions**

- The chip should be stored in a dry, nitrogen-filled environment and used in an ultraclean environment;
- GaAs material is brittle and the chip surface cannot be touched. Be careful when using it;
- Sinter the chip with conductive glue or alloy (the alloy temperature cannot exceed 300 °C and the time cannot exceed 30 seconds) to ensure that it is fully grounded;
- The gap between the chip microwave port and the substrate should not exceed 0.05mm. Use 25µm double gold wire bonding. The recommended gold wire length is 250 to 400µm;
- There are no DC blocking capacitors at the chip input and output terminals;
- The chip is sensitive to static electricity. Please pay attention to anti-static measures during storage and use.